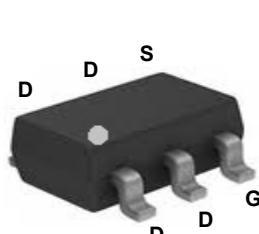
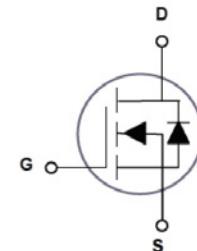


Main Product Characteristics

$BV_{(BR)DSS}$	150V
$R_{DS(ON)}$	480mΩ
I_D	1.4A



SOT-23-6L



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for hand-held devices, battery protection and load switch
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSF02N15 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current – Continuous ($T_c=25^\circ\text{C}$)	I_D	1.4	A
Drain Current – Continuous ($T_c=100^\circ\text{C}$)		0.88	A
Drain Current – Pulsed ¹	I_{DM}	5.6	A
Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	1.56	W
Power Dissipation – Derate above 25°C		0.012	W/ $^\circ\text{C}$
Storage Temperature Range	T_{STG}	-50 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-50 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	80	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	150	---	---	V
Drain-Source Leakage Current	I_{DS}	$\text{V}_{\text{DS}}=150\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$\text{V}_{\text{DS}}=120\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
Gate-Source Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	±100	nA
On Characteristics						
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=1\text{A}$	---	380	480	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=6\text{V}$, $\text{I}_D=0.5\text{A}$	---	410	520	$\text{m}\Omega$
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	2	3	4	V
Forward Transconductance	g_{fs}	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_D=1\text{A}$	---	1.7	---	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{2,3}	Q_g	$\text{V}_{\text{DS}}=75\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=1\text{A}$	---	8.1	16	nC
Gate-Source Charge ^{2,3}	Q_{gs}		---	2	4	
Gate-Drain Charge ^{2,3}	Q_{gd}		---	2.7	5.4	
Turn-On Delay Time ^{2,3}	$\text{T}_{\text{d(on)}}$	$\text{V}_{\text{DD}}=75\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_e=10\Omega$ $\text{I}_D=1\text{A}$	---	8.2	16	nS
Rise Time ^{2,3}	T_r		---	5.8	12	
Turn-Off Delay Time ^{2,3}	$\text{T}_{\text{d(off)}}$		---	14.8	28	
Fall Time ^{2,3}	T_f		---	8	16	
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=25\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	350	700	pF
Output Capacitance	C_{oss}		---	34	68	
Reverse Transfer Capacitance	C_{rss}		---	26	52	
Gate Resistance	R_g	$\text{V}_{\text{GS}}=0\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	2	4	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_s	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	1.4	A
Pulsed Source Current	I_{SM}		---	---	2.8	A
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
Reverse Recovery Time	t_{rr}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $\text{di}/\text{dt}=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	43	---	nS
Reverse Recovery Charge	Q_{rr}		---	37	---	nC

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

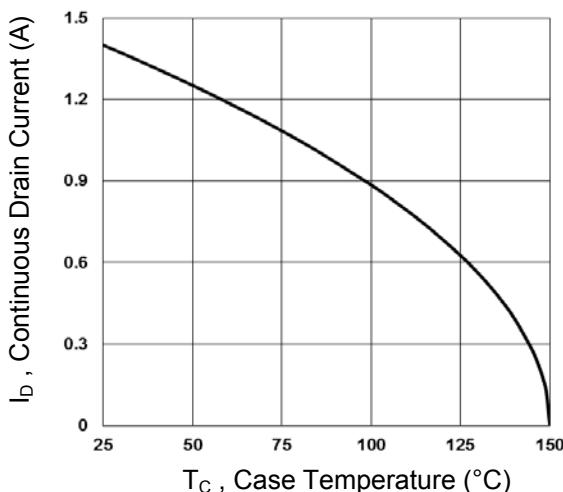


Fig.1 Continuous Drain Current vs. T_c

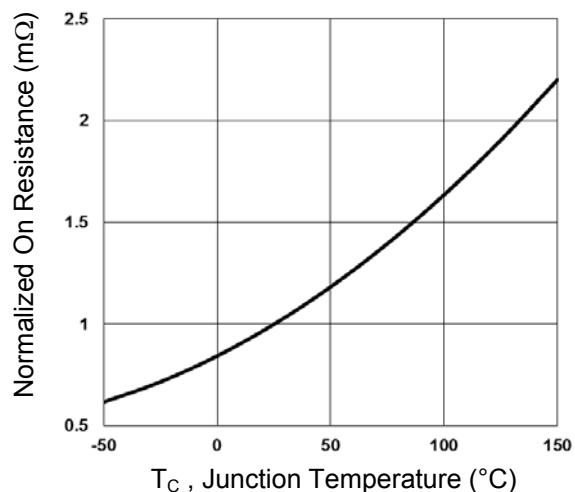


Fig.2 Continuous Drain Current vs. T_c

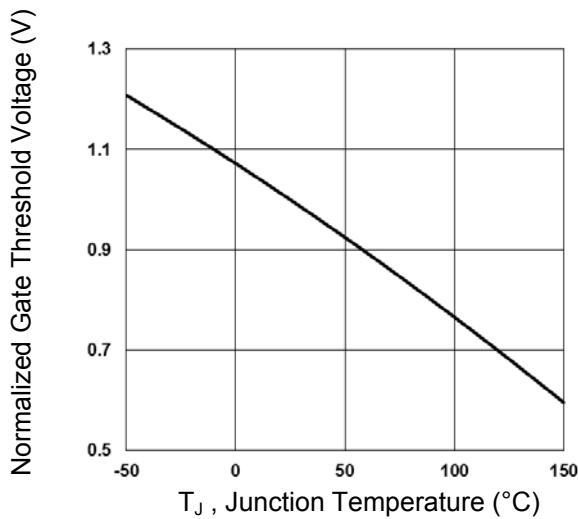


Fig.3 Normalized V_{th} vs. T_j

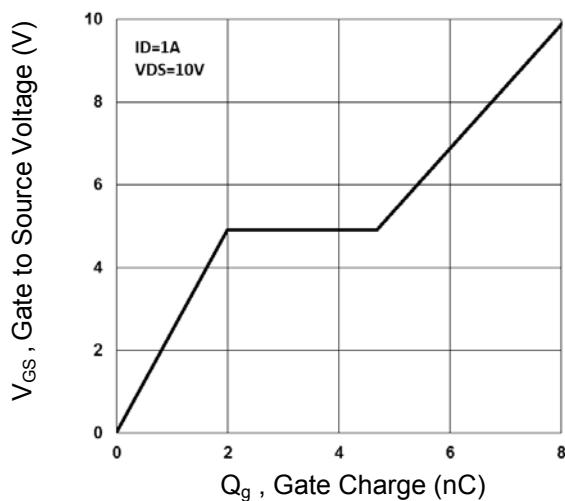


Fig.4 Gate Charge Waveform

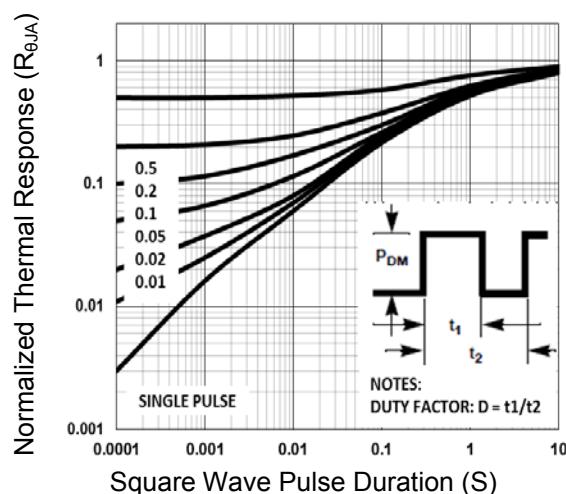


Fig.5 Normalized Transient Impedance

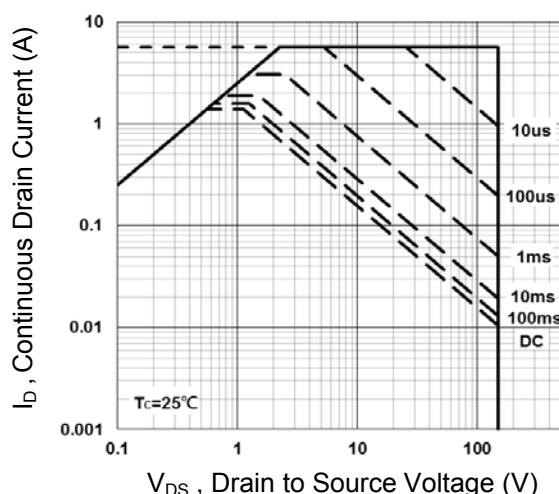


Fig.6 Maximum Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

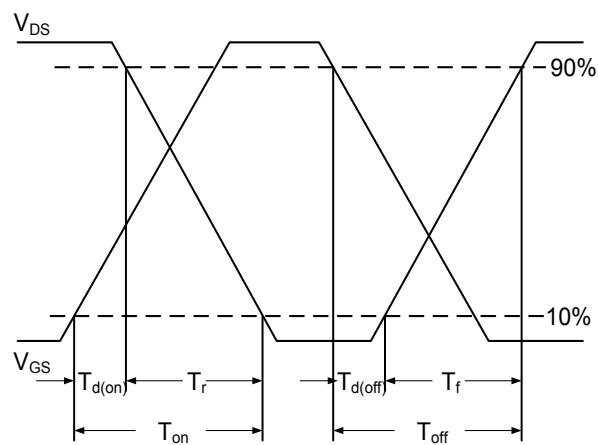


Fig.7 Switching Time Waveform

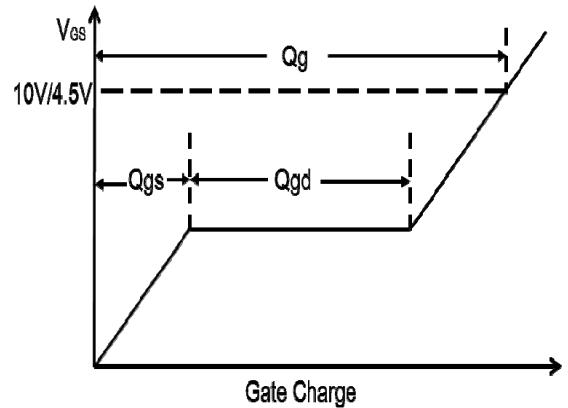
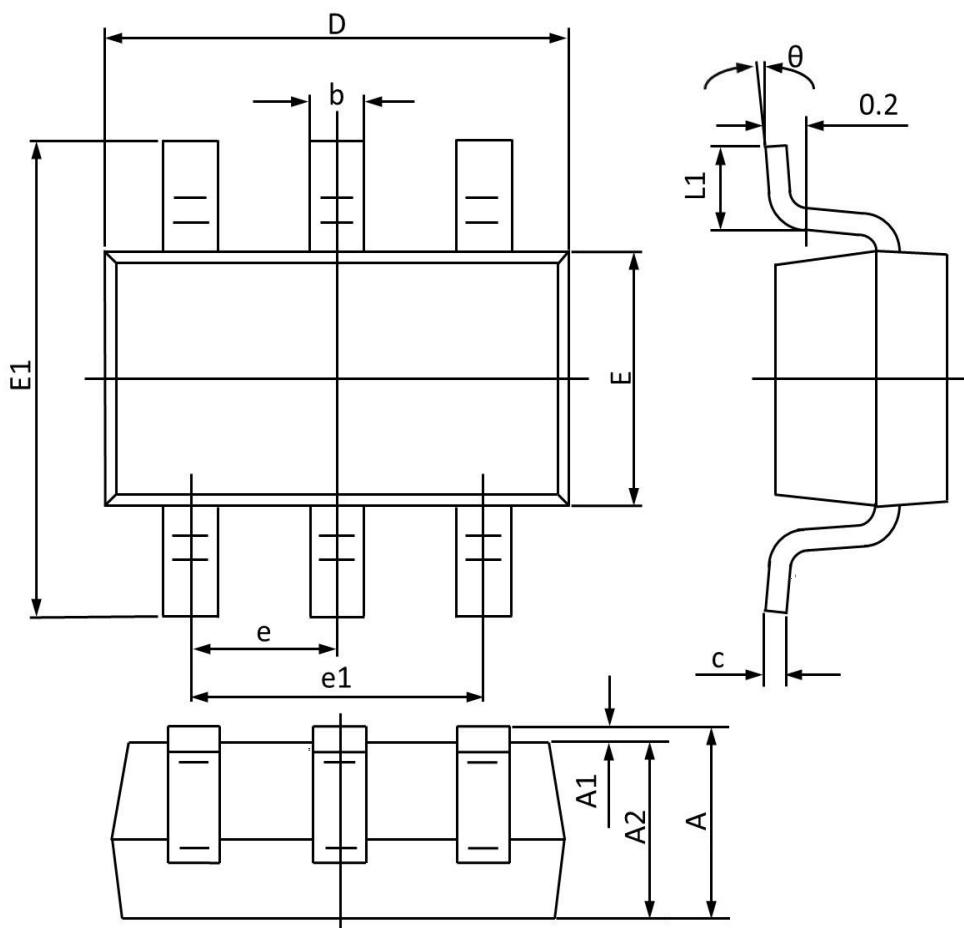


Fig.8 E_{AS} Waveform

SOT23-6 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.450	-	0.057	-
A1	0.100	0.000	0.004	0.000
A2	1.300	1.050	0.051	0.041
b	0.500	0.300	0.020	0.012
c	0.200	0.100	0.008	0.004
D	3.100	2.700	0.122	0.106
E	1.800	1.400	0.071	0.055
E1	3.000	2.600	0.118	0.102
e	0.95 BSC		0.037 BSC	
e1	2.000	1.800	0.079	0.071
L1	0.600	0.300	0.024	0.012
θ	10 °	0 °	10 °	0 °